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Examiner: Lee D. Wilson
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LISTING OF CLAIMS

1-26 (canceled)

27. (New) A method for forming a chemical mechanical polishing pad, comprising an interior segment and an outer surface, said method comprising:

- (a) providing the interior segment of the chemical mechanical polishing pad;
- (b) coating the interior segment of the chemical mechanical polishing pad with a metal film, to form the outer surface of the chemical mechanical polishing pad;

wherein the outer surface is at least 0.05 microns thick and wherein the coating occurs by at least one method selected from the group consisting of vacuum metallization, sputtering and electroless plating.